

# **Pin Descriptions**

Package: X1-DFN1216-4

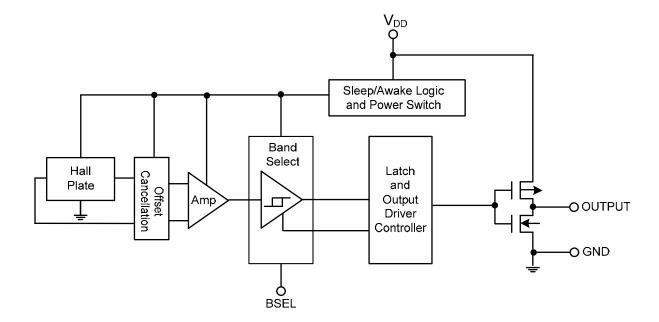
Pin Number	Pin Name	Function	
1	OUTPUT	Output Pin	
2	$V_{DD}$	Power Supply Input	
3	BSEL	Band Select	
4	GND	Ground Pin	

Package: SOT553

Pin Number	Pin Name	Function
1	$V_{DD}$	Power Supply Input
2	NC	No Connection (Note 5)
3	BSEL	Band Select
4	GND	Ground
5	OUTPUT	Output

Note: 5. NC is "No Connection" pin and is not connected internally. This pin can be left open or tied to ground.

# **Functional Block Diagram**





### Absolute Maximum Ratings (Note 6) (@TA = +25°C, unless otherwise specified.)

Symbol	Parameter		Rating	Unit
$V_{DD}$	Supply Voltage (Note 7)		6	V
$V_{DD\_REV}$	Reverse Supply Voltage		-0.3	V
I <sub>OUTPUT</sub>	Output current (source and sink)		3.5	mA
В	Magnetic Flux Density		Unlimited	
В	Package Power Dissipation	X1-DFN1216-4	230	mW
$P_{D}$	Package Power Dissipation	SOT553	230	mW
Ts	Storage Temperature Range		-65 to +150	°C
TJ	Maximum Junction Temperature	150	°C	
ESD HBM	Human Rady Madal (HMR) ESD canability	VDD, GND and OUTPUT pins	8	kV
EOD UDINI	Human Body Model (HMB) ESD capability	BSEL pin	6	kV

Notes:

### Recommended Operating Conditions (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Rating	Unit
$V_{DD}$	Supply Voltage	Operating	1.6V to 3.6V	V
T <sub>A</sub>	Operating Temperature Range	Operating	-40 to +85	°C

# **Electrical Characteristics** (@ $T_A = +25$ °C, $V_{DD} = 1.85$ V, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>OL</sub>	Output Low Voltage (on)	$I_{OUT} = 1mA$	_	0.1	0.2	V
V <sub>OH</sub>	Output High Voltage (off)	$I_{OUT} = -1 \text{mA}$	V <sub>DD</sub> -0.2	V <sub>DD</sub> -0.1		V
loff	Output Leakage Current	$V_{OUT} = 3.6V$ , Output off	-	< 0.1	1	μΑ
$V_{SEL\_LB}$	BSEL pin input voltage – Low Band		0	_	0.5	V
V <sub>SEL_HB</sub>	BSEL pin input voltage – High Band		1.4	_	3.6	V
R <sub>PD_BSEL</sub>	BSEL pin internal pull-down resistor	(Note 8)	_	50	_	kΩ
I <sub>DD</sub> (awake)	Supply Current	During 'awake' period, T <sub>A</sub> = +25°C, V <sub>DD</sub> = 3V	_	2.1		mA
I <sub>DD</sub> (sleep)	-Supply Current	During 'sleep' period, T <sub>A</sub> = +25°C, V <sub>DD</sub> = 3V	_	2.5	_	mA
1 (00)	Average Cumply Current	$T_A = +25^{\circ}C, V_{DD} = 1.85V$	_	4.3	8	μΑ
I <sub>DD</sub> (avg)	Average Supply Current	T <sub>A</sub> = +25°C, V <sub>DD</sub> = 3.6V	_	7.2	13	μA
Tawake	Awake Time	(Note 9)	_	50	100	μs
Tperiod	Period	(Note 9)	_	50	100	ms
D.C.	Duty Cycle	(Note 10)	_	0.1		%

Notes

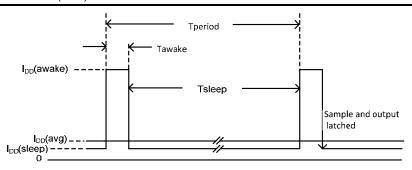
- 8. BSEL pin internal pull-down resistor is only active during AWAKE time
- When power is initially on, the operating V<sub>DD</sub> (1.6V to 3.6V) must be applied to guarantee the output sampling.
  The output state is valid after the second operating phase (typical 100ms).
- 10. Transition time varies dependant on the timing of BSEL activation during the sleep and awake phases.

<sup>6.</sup> Stresses greater than the 'Absolute Maximum Ratings' specified above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

<sup>7.</sup> The absolute maximum V<sub>DD</sub> of 6V is a transient stress rating and is not meant as a functional operating condition. It is not recommended to operate the device at the absolute maximum rated conditions for any period of time.



### **Electrical Characteristics (cont.)**



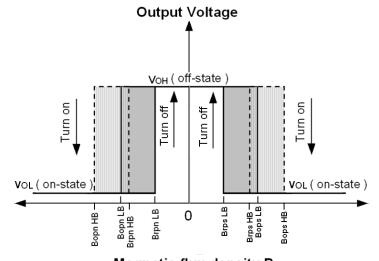
## Magnetic Characteristics (Note 11 &12) (T<sub>A</sub> = -40°C to +85°C, V<sub>DD</sub> = 1.85V, unless otherwise specified)

					(1mT=10	Gauss)
BSEL	Symbol	Characteristics	Min	Тур	Max	Unit
Low	Bops <sub>LB</sub> (South pole to part marking side)	Law Band Operation Boint	15	30	45	
Low	Bopn <sub>LB</sub> (North pole to part marking side)	Low Band - Operation Point	-45	-30	-15	
Low	Brps <sub>LB</sub> (South pole to part marking side)	Low Band - Release Point	10	20	35	
Low	Brpn <sub>LB</sub> (North pole to part marking side)	Low Baria - Release Politi	-35	-20	-10	
High	Bops <sub>HB</sub> (South pole to part marking side)	Lligh Road Operation Point	25	40	55	Gauss
High	Bopn <sub>HB</sub> (North pole to part marking side)	High Band - Operation Point	-55	-40	-25	
High	Brps <sub>HB</sub> (South pole to part marking side)	High Book Balance Brief		30	45	
High	Brpn <sub>HB</sub> (North pole to part marking side)	High Band - Release Point	-45	-30	-20	
_	Bhy ( Bopx - Brpx )	Hysteresis	_	10	_	

Notes:

- 11. Typical data is at  $T_A = +25$ °C,  $V_{DD} = 1.85$ V.
- 12. Maximum and minimum parameters values over the operating temperature range are not tested in production, they are guaranteed by design, process control and characterization. The magnetic characteristics may vary with supply voltage, operating temperature and after soldering.

The AH1894 includes a band select pin (BSEL) so that the operate (Bops and Bopn) and release (Brps and Brpn) points can be adjusted between two pre-defined ranges. The BSEL can be hard wired within the application circuit or the band can be selected on the fly by using the BSEL pin as a logic input. This feature allows the AH1894 sensitivity to be changed by firmware within the application without the addition of any external components. If the BSEL pin is left open circuit the AH1894 defaults to low band.



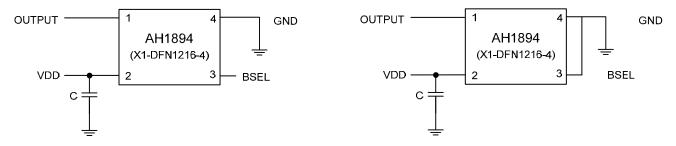
Magnetic flux density B



# **Application Notes**

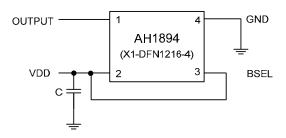
#### Applications Circuit 1 - Low Band

Leaving the BSEL pin unconnected or connecting the BSEL pin to ground permanently configures the AH1894 into its high sensitivity mode (lower switching thresholds), requiring a reduced magnetic flux density to activate its output (Low Band).



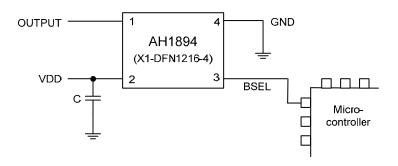
#### Applications Circuit 2 - High Band

Connecting the BSEL pin to  $V_{DD}$  or applying a voltage greater than 1.4V configures the AH1894 into its low sensitivity mode (higher switching threshold), requiring a higher magnetic flux density to activate its output (High Band).



#### Applications Circuit 3 - Adjustable Sensitivity

To enhance the flexibility within the application the sensitivity can be adjusted with a standard logic signal allowing it to be controlled by a microcontroller or a logic source. This allows the sensitivity to be changed within the application without a hardware change. Whenever the sensitivity band selection is changed, allow for band selection changeover to complete and output to be valid.

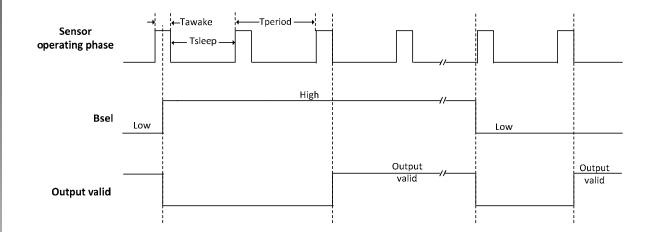




# **Application Notes** (cont.)

### **Bands Select Change Timing and Valid Output**

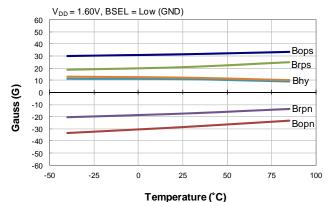
Whenever band selection BSEL pin input is changed, allow for band selection changeover to complete and stabilize. The output is valid only after the second complete operating 'awake' phase after the band selection change is complete. Time taken for the output to be valid, after the BSEL change, depends on timing of BSEL change during the sleep and awake phase; this time is up to 100ms typical and 200.1ms maximum (TBC).



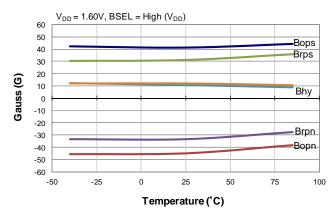


# **Typical Operating Characteristics**

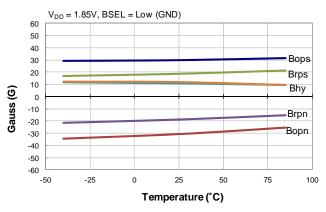
### Typical Switch Points Characteristics in Low Band (BSEL = Low) and High Band (BSEL = High)



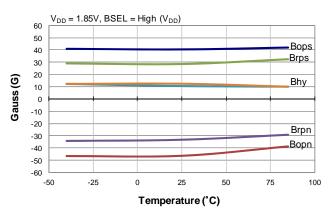
Switch Points vs Temperature



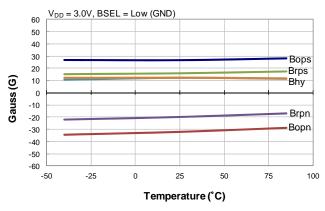
**Switch Points vs Temperature** 



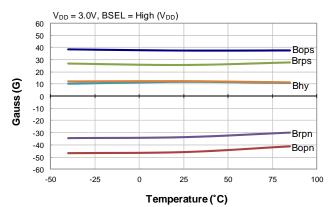
**Switch Points vs Temperature** 



Switch Points vs Temperature



Switch Points vs Temperature

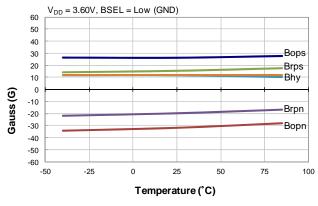


**Switch Points vs Temperature** 

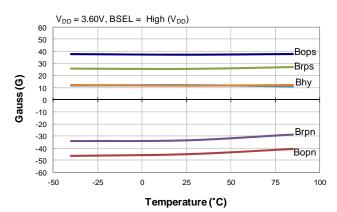


# **Typical Operating Characteristics (cont.)**

### Typical Switch Points Characteristics in Low Band (BSEL = Low) and High Band (BSEL = High)

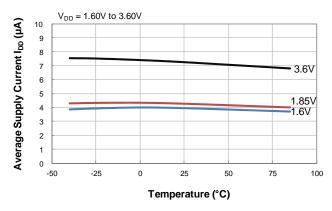


**Switch Points vs Temperature** 

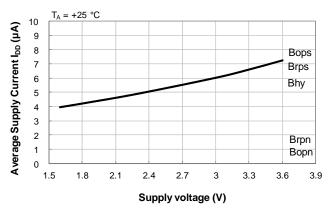


**Switch Points vs Temperature** 

#### Average Supply Current IDD (avg)



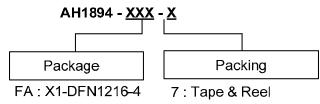
Average Supply Current vs. Temperature



Average Supply Current vs. Supply Voltage



## **Ordering Information**



Z:SOT553

Part Number	Package	Pookoging	7" Tape a	nd Reel
Part Number	Code	Packaging	Quantity	Part Number Suffix
AH1894-FA-7	FA	X1-DFN1216-4	3000/Tape & Reel	-7
AH1894-Z-7	Z	SOT553	3000/Tape & Reel	-7

## **Marking Information**

(1) Package Type: X1-DFN1216-4



 $\mathbf{X}$   $\mathbf{X}$ YWX Pin 1 indicator

XX: Identification Code

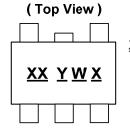
<u>Y</u> : Year : 0~9

 $\underline{\underline{W}}$ : Week: A~Z: 1~26 week; a~z: 27~52 week; z represents

52 and 53 week X : A~Z : Green

Part Number	Package	Identification Code
AH1894-FA-7	X1-DFN1216-4	B4

(2) Package Type: SOT553



 $\frac{XX}{Y}: \mbox{Identification Code} \\ \frac{Y}{Y}: \mbox{Year: 0 to 9}$ 

 $\underline{W}$ : Week: A to Z: 1~26 week;

a to z: 27~52 week; z represents 52 and 53 week

X: Internal code

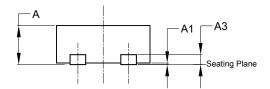
Part Number	Package	Identification Code
AH1894-Z-7	SOT553	B4

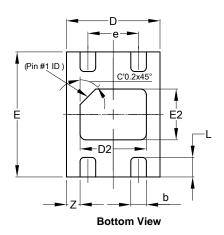


## Package Outline Dimensions (All dimensions in mm.)

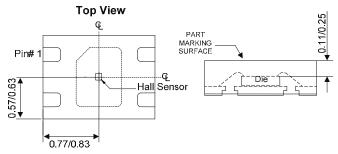
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

### (1) Package Type: X1-DFN1216-4





	X1-DFN1216-4				
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.02		
A3			0.13		
b	0.15	0.25	0.20		
D	1.15	1.25	1.20		
D2	0.75	0.95	0.85		
E	1.55	1.65	1.60		
E2	0.55	0.75	0.65		
е	-	-	0.65		
L	0.20	0.30	0.25		
Z	-	-	0.175		
All D	imens	ions in	mm		

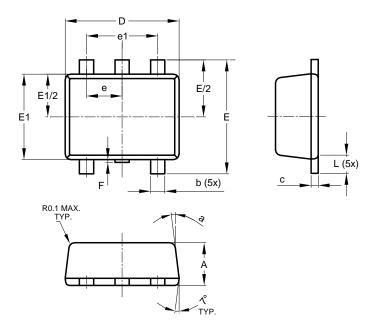


**Sensor Location** 

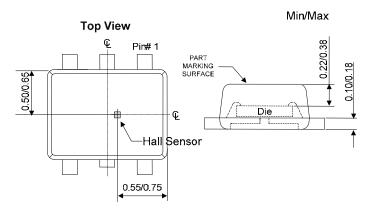


# Package Outline Dimensions (cont.) (All dimensions in mm.)

### (2) Package Type: SOT553



	SOT553					
Dim	Min	Max	Тур			
Α	0.55	0.62	0.60			
b	0.15	0.30	0.20			
С	0.10	0.18	0.15			
D	1.50	1.70	1.60			
Е	1.55	1.70	1.60			
E1	1.10	1.25	1.20			
е	(	).50 BS(				
e1	1	1.00 BS0				
F	0.00	0.10	_			
L	0.10	0.30	0.20			
а	6°	8°	7°			
All [	Dimensi	ons in i	mm			



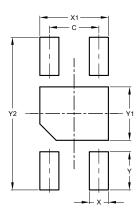
**Sensor Location** 



# **Suggested Pad Layout**

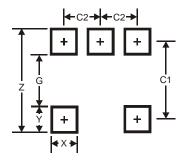
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

### (1) Package Type: X1-DFN1216-4



X1-DFN1216-4				
Dimensions	Value			
С	0.65			
Х	0.25			
X1	0.90			
Y	0.50			
Y1	0.70			
<b>Y2</b> 2.00				
All Dimensions in mm				

### (2) Package Type: SOT553



SOT553	
Dimensions	Value
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5
All Dimensions in mm	



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